

ABSTRACT

To provide a mask that it becomes possible to perform destructive inspection without a mask for inspection or to perform more accurately non-destructive inspection and a method of inspecting the same. A mask comprising a thin film for exposure that has a transmission portion and a non-transmission portion of a beam for exposure, a thick film portion that is formed around the thin film for exposure and that supports the thin film for exposure, and a thin film for inspection that has a transmission portion and a non-transmission portion of the beam for exposure, that is formed at a distance from a thin film for exposure and that has thickness and material equal to those of a thin film for exposure, and a method of inspection of a mask that inspection is performed by using a thin film for inspection, and a method of producing a semiconductor device that lithography is performed by using a thin film for exposure of the mask.